

1. Features

- Uses advanced SGT technology
- Extremely low $R_{DS(on)}$.typ=1.25m Ω @ $V_{GS}=10V$
- Excellent gate charge x $R_{DS(on)}$ product(FOM)

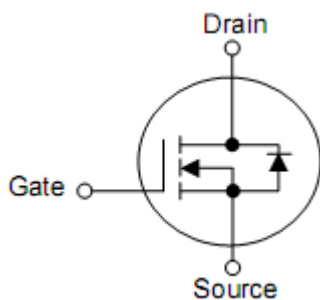
2. Application

- Motor control and drives
- Battery management
- DC/DC Converters
- General purpose applications

3. Pin configuration



TOLL-8



| Pin | Function |
|---------------|----------|
| 1 | Gate |
| 9 | Drain |
| 2,3,4,5,6,7,8 | Source |

4. Ordering Information

| Part Number | Package | Brand |
|-------------|---------|-------|
| KCT1808A | TOLL-8 | KIA |

5. Absolute maximum ratings

$T_C=25\text{ }^\circ\text{C}$ unless otherwise specified

| Parameter | Symbol | Ratings | Unit |
|---|-------------------|---|------------------|
| Drain-to-Source Voltage | V_{DS} | 80 | V |
| Continuous Drain Current | I_D | $T_C=25\text{ }^\circ\text{C}$ (Silicon limited) | 260 |
| | | $T_C=25\text{ }^\circ\text{C}$ (Package limited) | 240 |
| | | $T_C=100\text{ }^\circ\text{C}$ (Silicon limited) | 170 |
| Pulsed drain current ($T_C = 25\text{ }^\circ\text{C}$, t_p limited by T_{Jmax}) | I_{DP} | 750 | A |
| Avalanche energy, single pulse ($L=0.5\text{mH}$, $R_g=25\Omega$) | E_{AS} | 2862 | mJ |
| Gate-Source voltage | V_{GS} | ± 20 | V |
| Power dissipation | P_{tot} | 250 | W |
| Junction & Storage Temperature Range | T_J & T_{STG} | -55 to 150 | $^\circ\text{C}$ |

6. Thermal characteristics

| Parameter | Symbol | Ratings | Units |
|--------------------------------------|-----------------|---------|--------------------|
| Thermal resistance, Junction-case | $R_{\theta JC}$ | 0.5 | $^\circ\text{C/W}$ |
| Thermal resistance, junction-ambient | $R_{\theta JA}$ | 52 | $^\circ\text{C/W}$ |

7. Electrical characteristics

($T_J=25^{\circ}\text{C}$, unless otherwise notes)

| Parameter | Symbol | Test Condition | Value | | | Unit |
|------------------------------------|---------------|---|-------|-------|------|------------|
| | | | min. | typ. | max. | |
| Drain-source breakdown voltage | $V_{(BR)DSS}$ | $V_{GS}=0V, I_D=250\mu A$ | 80 | - | - | V |
| Gate threshold voltage | $V_{GS(th)}$ | $V_{DS}=V_{GS}, I_D=250\mu A, T_J=25^{\circ}\text{C}$ | 2 | 3 | 4 | V |
| Zero gate voltage drain current | I_{DSS} | $V_{DS}=80V, V_{GS}=0V, T_J=25^{\circ}\text{C}$ | - | - | 1 | μA |
| | | $V_{DS}=64V, V_{GS}=0V, T_J=125^{\circ}\text{C}$ | - | - | 10 | μA |
| Gate-source leakage current | I_{GSS} | $V_{GS}=20V, V_{DS}=0V$ | - | - | 100 | nA |
| Drain-source on-state resistance | $R_{DS(on)}$ | $V_{GS}=10V, I_D=50A, T_J=25^{\circ}\text{C}$ | - | 1.25 | 2 | m Ω |
| Transconductance | g_{fs} | $V_{DS}=5V, I_D=40A$ | - | 227 | - | S |
| Input Capacitance | C_{iss} | $V_{GS}=0V, V_{DS}=40V, f=1\text{MHz}$ | - | 15022 | - | pF |
| Output Capacitance | C_{oss} | | - | 2523 | - | |
| Reverse Transfer Capacitance | C_{rss} | | - | 1303 | - | |
| Gate Total Charge | Q_G | $V_{GS}=10V, V_{DS}=40V, I_D=50A$ | - | 205 | - | nC |
| Gate-Source charge | Q_{gs} | | - | 54 | - | |
| Gate-Drain charge | Q_{gd} | | - | 46 | - | |
| Turn-on delay time | $t_{d(on)}$ | $T_J=25^{\circ}\text{C}, V_{GS}=10V, V_{DS}=40V, R_L=3\Omega$ | - | 38 | - | ns |
| Rise time | t_r | | - | 132 | - | |
| Turn-off delay time | $t_{d(off)}$ | | - | 126 | - | |
| Fall time | t_f | | - | 153 | - | |
| Gate resistance | R_G | $V_{GS}=0V, V_{DS}=0V, f=1\text{MHz}$ | - | 1.85 | - | Ω |
| Body Diode Forward Voltage | V_{SD} | $V_{GS}=0V, I_{SD}=50A$ | - | 0.8 | 1.2 | V |
| Body Diode Reverse Recovery Time | t_{rr} | $I_F=30A, dI/dt=500A/\mu s$ | - | 112 | - | ns |
| Body Diode Reverse Recovery Charge | Q_{rr} | $I_F=30A, dI/dt=500A/\mu s$ | - | 220 | - | nC |

8. Typical Characteristics

Fig 1: Output Characteristics

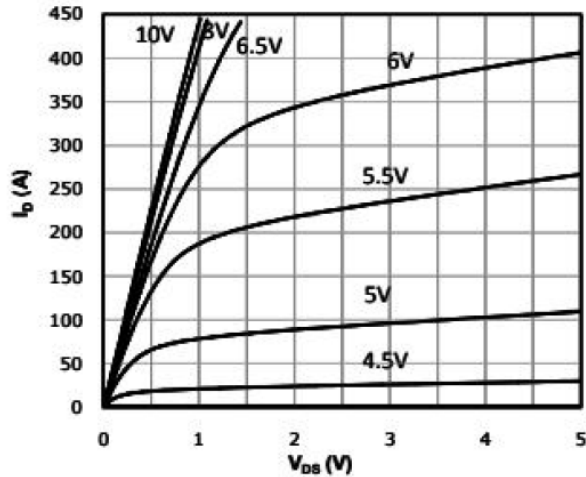


Fig 2: Transfer Characteristics

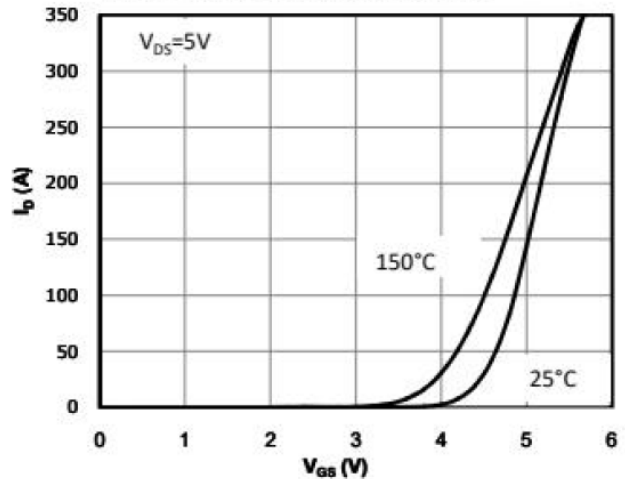


Fig 3: Rds(on) vs Drain Current and Gate Voltage

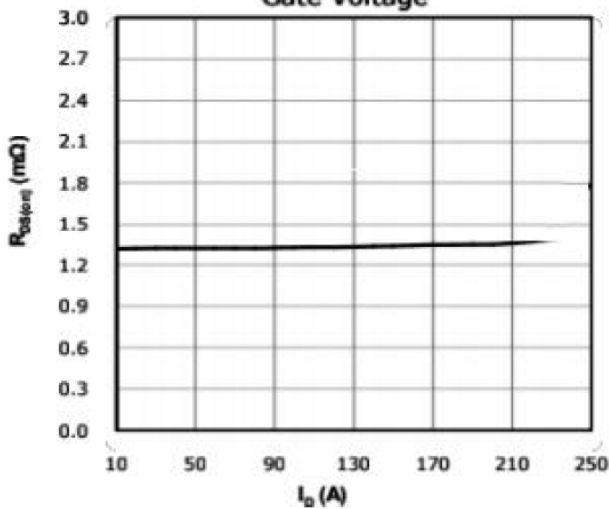


Fig 4: Rds(on) vs Gate Voltage

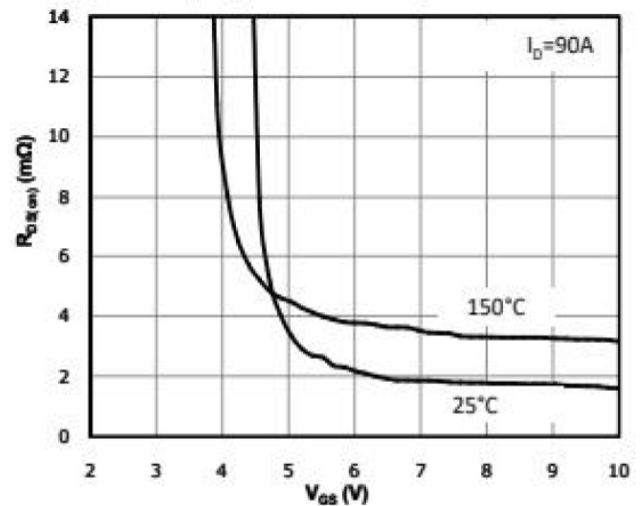


Fig 5: Rds(on) vs. Temperature

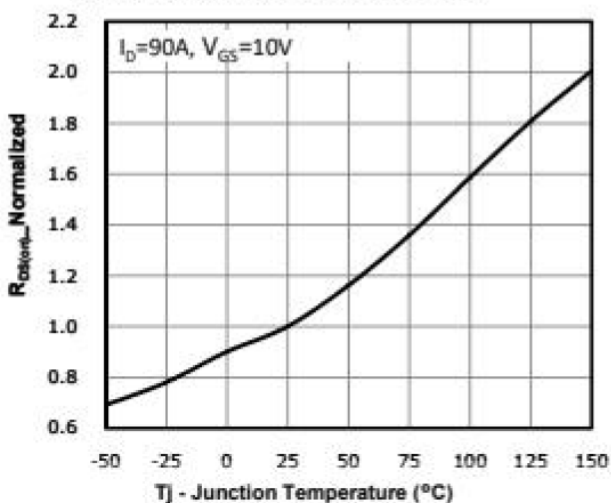


Fig 6: Capacitance Characteristics

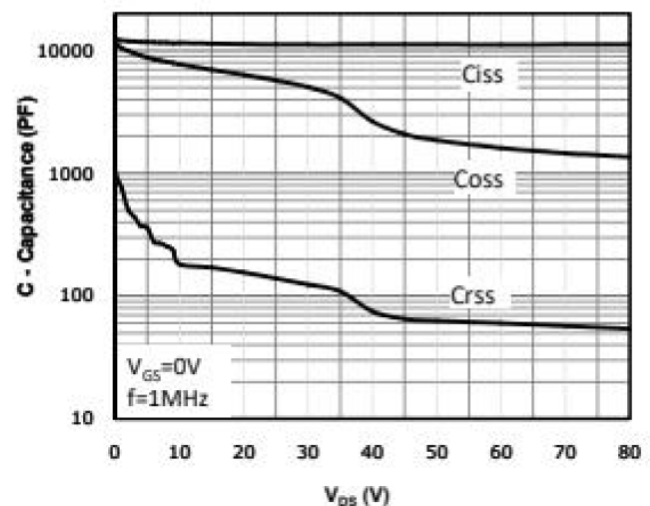


Fig 7: $V_{gs(th)}$ vs. Temperature

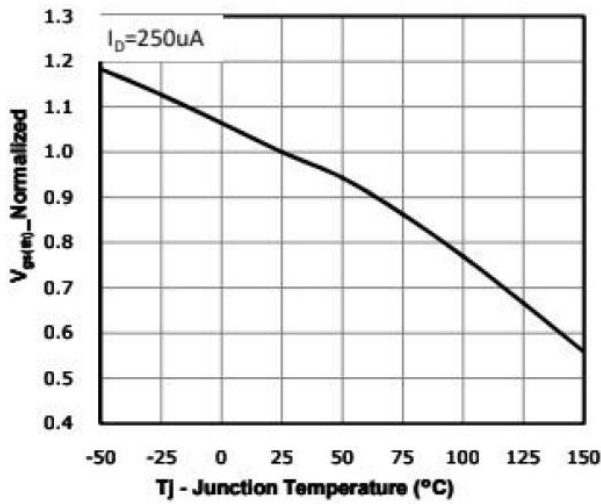


Fig 8: BV_{dss} vs. Temperature

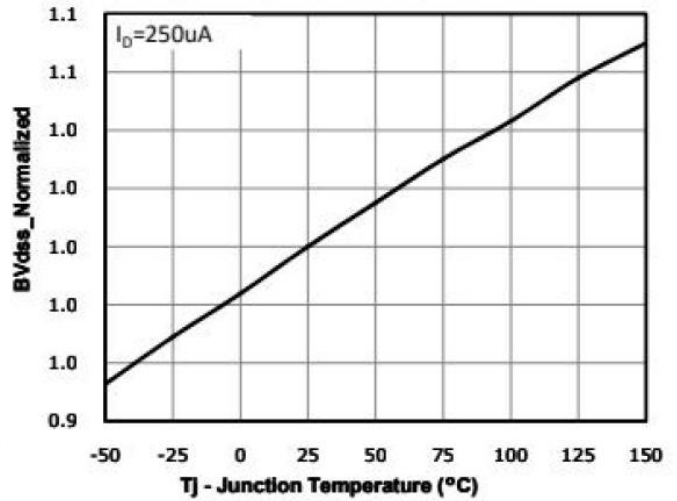


Fig 9: Gate Charge Characteristics

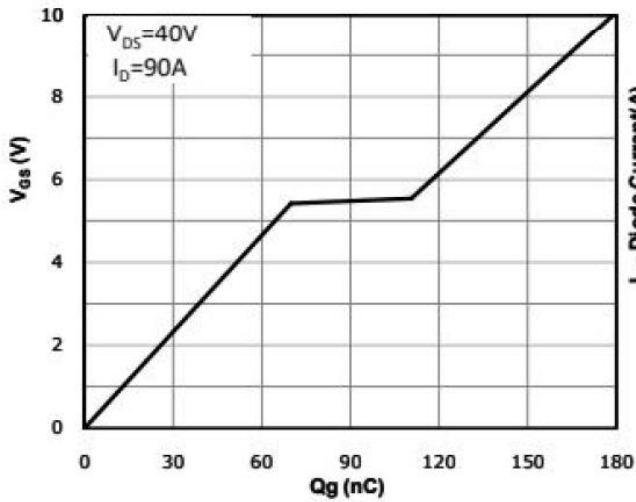


Fig 10: Body-diode Forward Characteristics

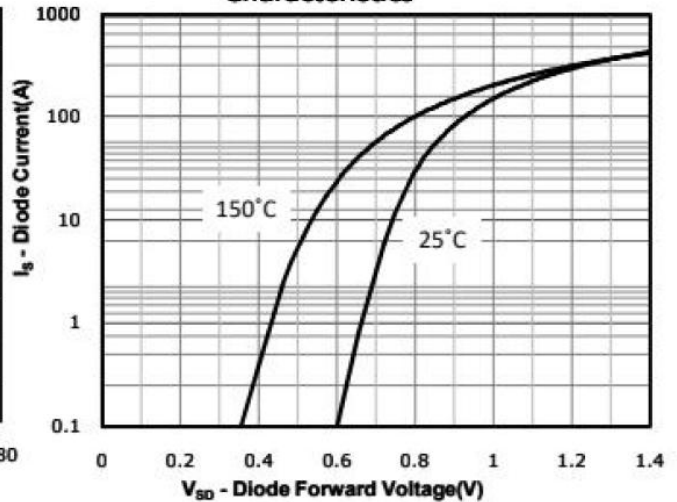


Fig 11: Power Dissipation

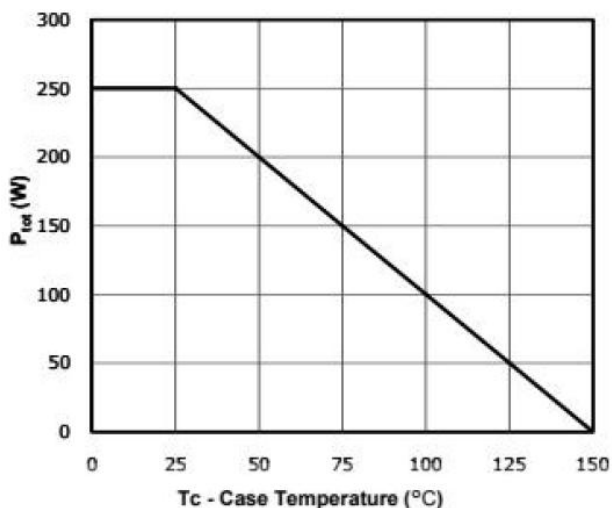


Fig 12: Drain Current Derating

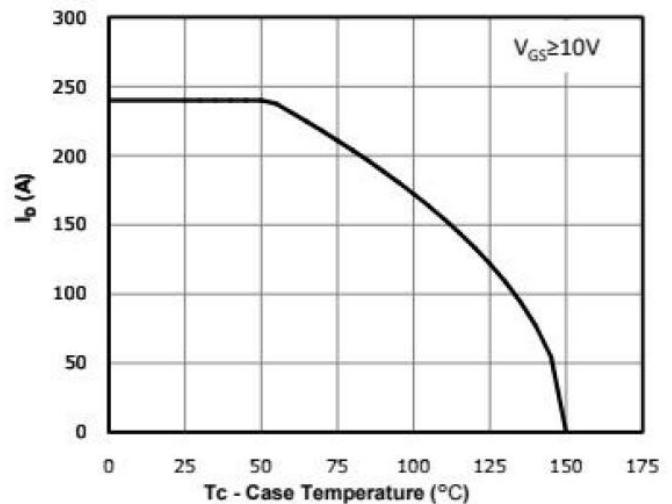


Fig 13: Safe Operating Area

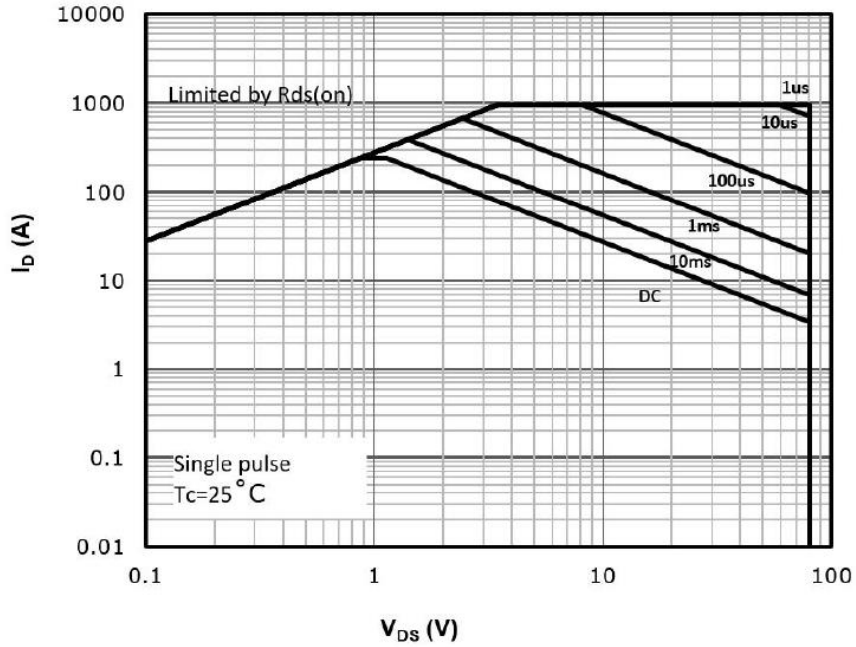
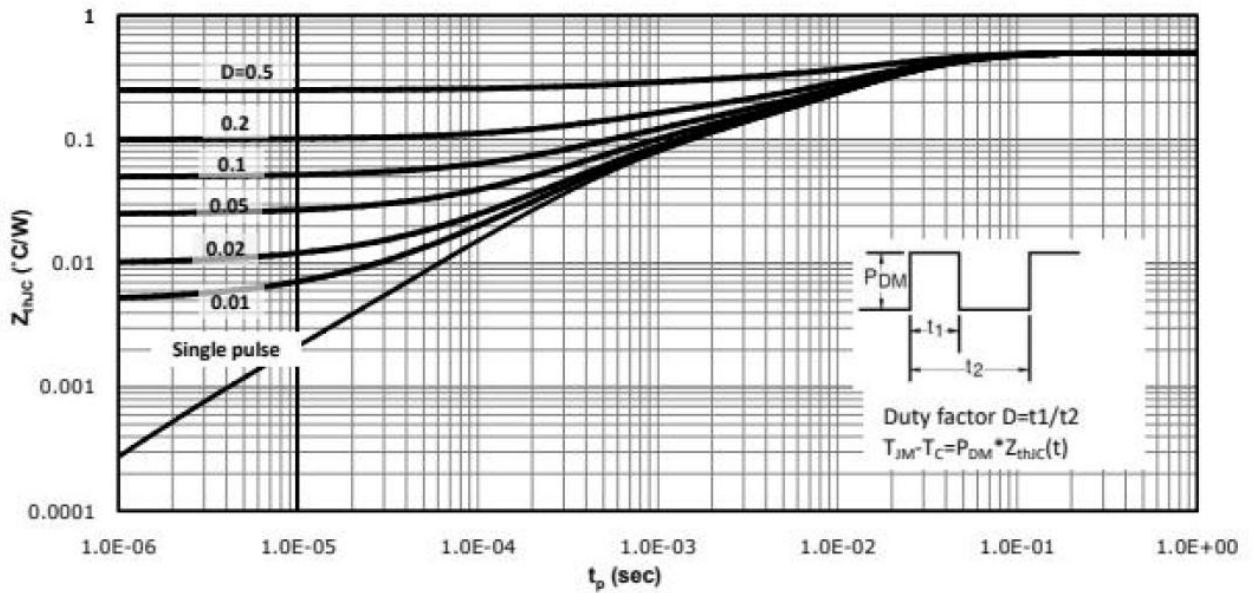
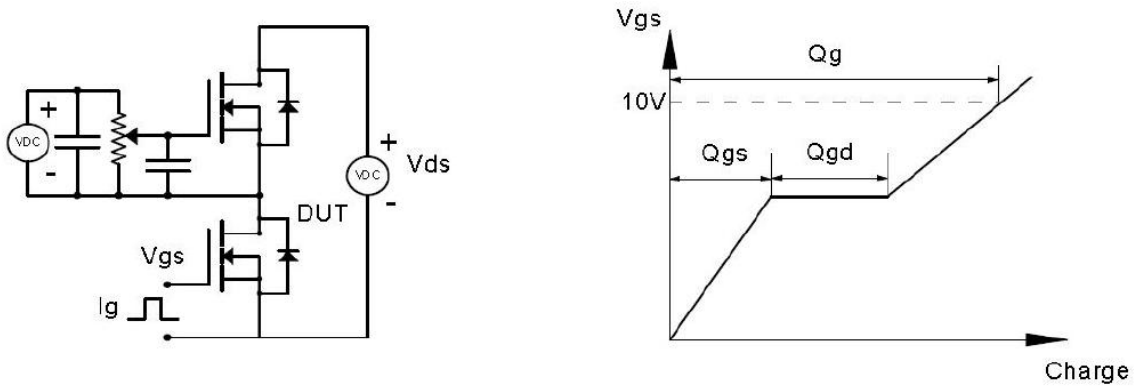


Fig 14: Max.Transient Thermal impedance

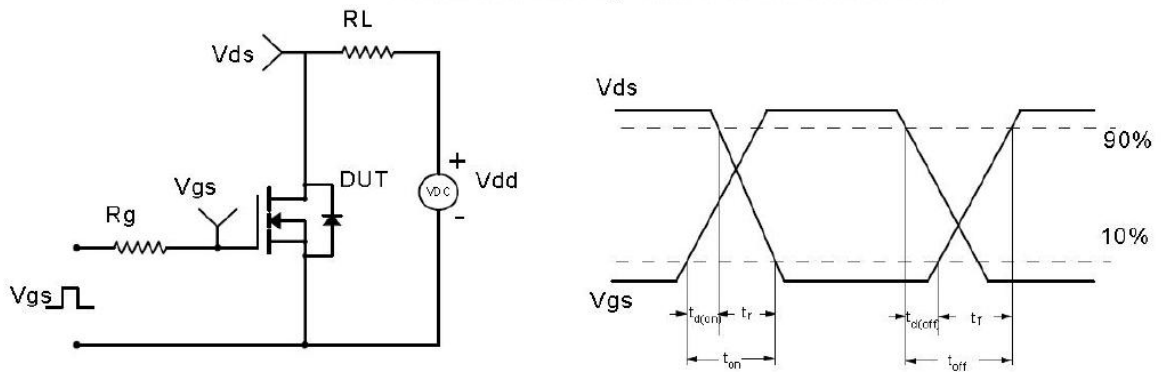


9. Test Circuit & Waveform

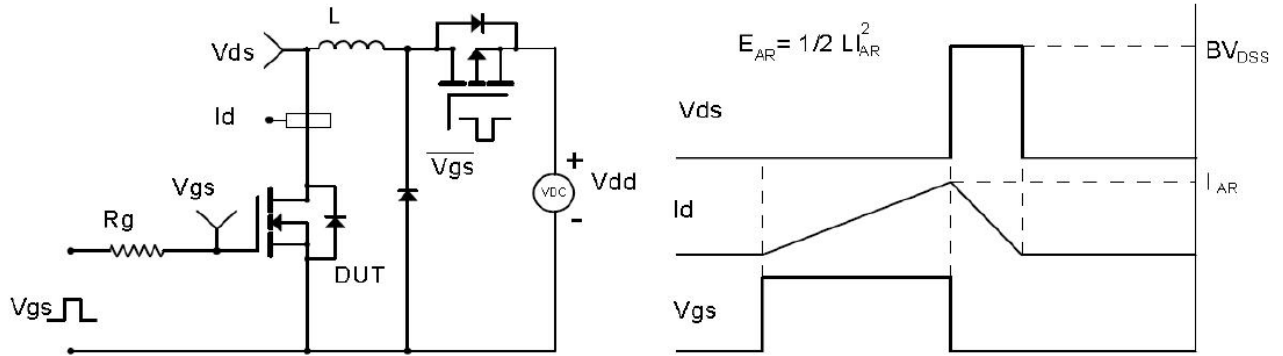
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

